

RJK2009DPM

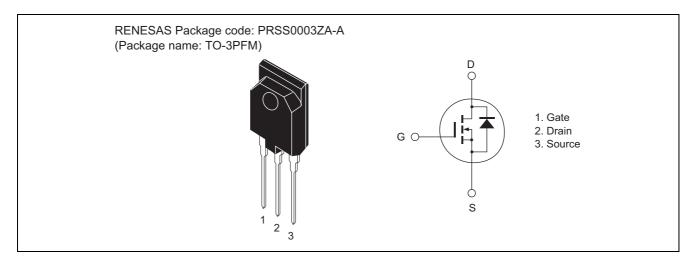
Silicon N Channel MOS FET High Speed Power Switching

REJ03G0474-0200 Rev.2.00 Aug.09.2005

Features

- Low on-resistance
- Low leakage current
- High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Symbol	Ratings	Unit
V_{DSS}	200	V
V_{GSS}	±30	V
I _D	40	Α
I _{D (pulse)} Note1	160	Α
I _{DR}	40	Α
I _{DR (pulse)} Note1	160	Α
I _{AP} Note3	40	Α
E _{AR} Note3	106	mJ
Pch Note2	60	W
θch-c	2.08	°C/W
Tch	150	°C
Tstg	-55 to +150	°C
	V _{DSS} V _{GSS} I _D I _{D (pulse)} Note1 I _{DR} I _{DR (pulse)} Note1 I _{DR (pulse)} Note1 I _{AP} Note3 E _{AR} Note3 Pch Note2 θch-c Tch	V _{DSS} 200 V _{GSS} ±30 I _D 40 I _{D(pulse)} Note1 160 I _{DR} 40 I _{DR (pulse)} Note1 160 I _{DR (pulse)} 40 160 I _{AP} Note3 40 E _{AR} Note3 106 Pch Note2 60 θch-c 2.08 Tch 150

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at Tc = 25°C

3. STch = 25° C, Tch $\leq 150^{\circ}$ C

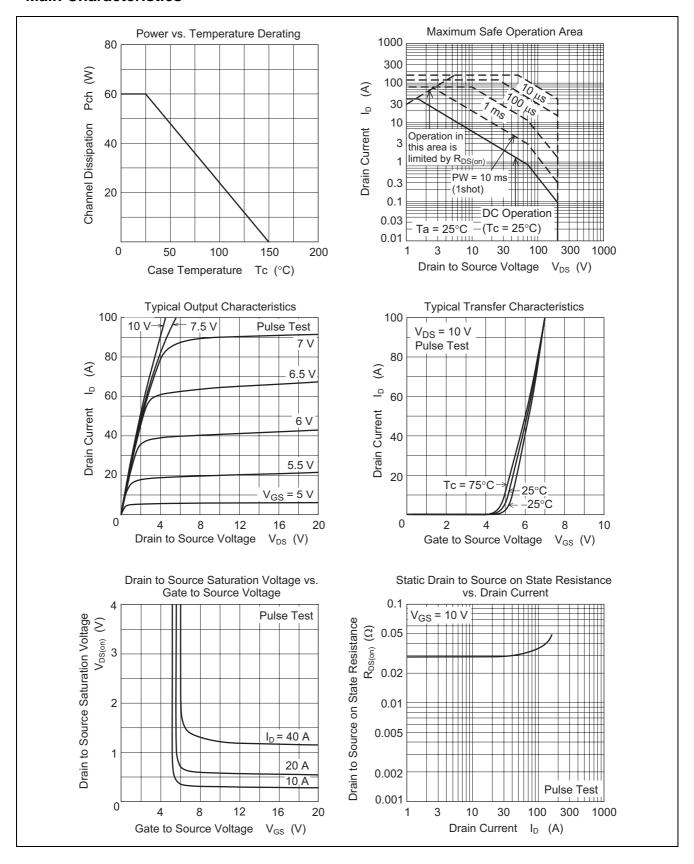
Electrical Characteristics

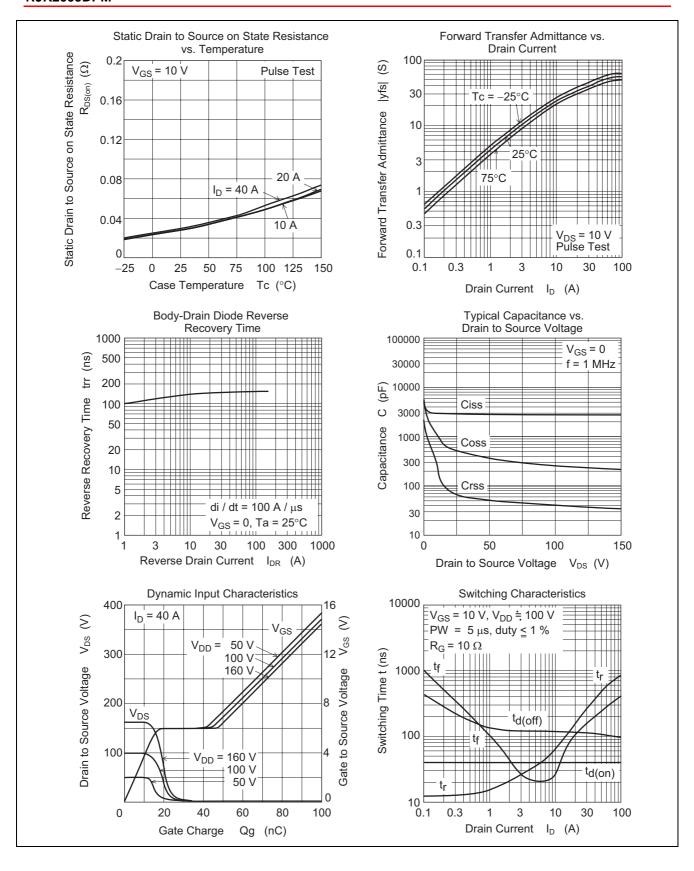
 $(Ta = 25^{\circ}C)$

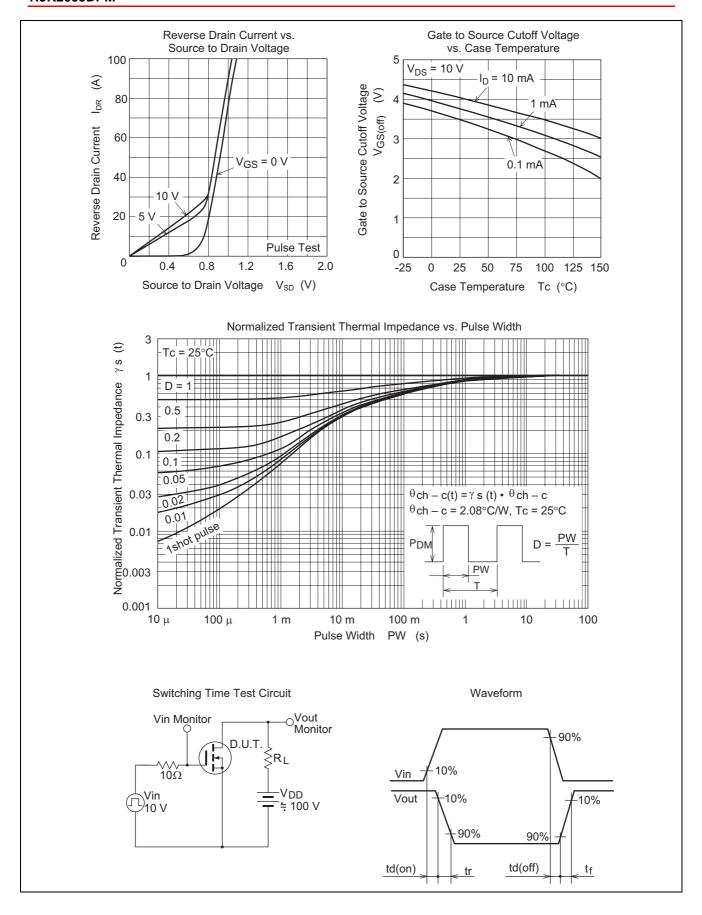
Item	Symbol	Min	Тур	Max	Unit	Test conditions	
Drain to source breakdown voltage	$V_{(BR)DSS}$	200		_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$	
Zero gate voltage drain current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 200 \text{ V}, V_{GS} = 0$	
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$	
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	
Forward transfer admittance	y _{fs}	20	33	_	S	$I_D = 20 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$	
Static drain to source on state	R _{DS(on)}	_	0.029	0.036	Ω	$I_D = 20 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$	
resistance							
Input capacitance	Ciss	_	2900	_	pF	$V_{DS} = 25 \text{ V}, V_{GS} = 0,$	
Output capacitance	Coss	—	520		pF	f = 1 MHz	
Reverse transfer capacitance	Crss	_	66	_	pF		
Turn-on delay time	t _{d(on)}	_	40	_	ns	$I_D = 20 \text{ A}, V_{GS} = 10 \text{ V},$	
Rise time	t _r	_	160	_	ns	$R_L = 5 \Omega$, $Rg = 10 \Omega$	
Turn-off delay time	t _{d(off)}	_	120	_	ns		
Fall time	t _f	_	110	_	ns		
Total gate charge	Qg	_	72	_	nC	$V_{DD} = 160 \text{ V}, V_{GS} = 10 \text{ V},$	
Gate to source charge	Qgs	_	16	_	nC	I _D = 40 A	
Gate to drain charge	Qgd	_	31	_	nC		
Body-drain diode forward voltage	V_{DF}	_	0.9	1.4	V	$I_F = 40 \text{ A}, V_{GS} = 0^{\text{Note4}}$	
Body-drain diode reverse recovery time	t _{rr}	_	150	_	ns	$I_F = 40 \text{ A}, V_{GS} = 0,$	
Body-drain diode reverse recovery charge	Q _{rr}	_	0.8	_	μС	diF/dt = 100 A/μs	

Notes: 4. Pulse test

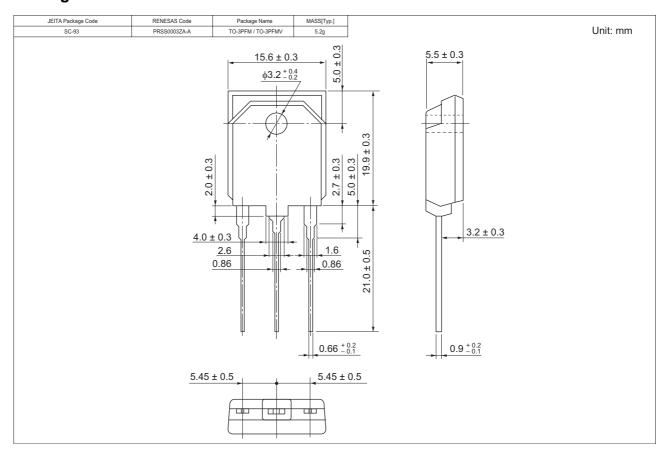
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
RJK2009DPM-E	30 pcs	Plastic magazine

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